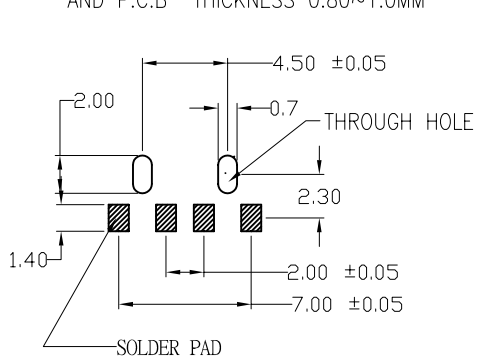


RECOMMEND P.C.B SMT PAD LAY OUT
AND P.C.B THICKNESS 0.80~1.0MM



NOTES:

1.0. MATERIALS :

- 1.1. ALL DIMENSIONS ARE IN M/M.
- 1.2. SHELL MATERIAL : SPCC T=0.30±0.02.
FINISH : 100u" Ni PLATED OVER COPPER UNDERPLATED.
- 1.3. INSULATOR MATERIAL : L.C.P. UL94V-0. Color in Black.
- 1.4. CONTACT AREA : 30u" MIN Ni OVER 3u" Au.
80u" MIN Sn/Cu IN SOLDER TAIL AREA.

2.0. RATING :

- 2.1. VOLTAGE : 30 VAC (R.M.S).
- 2.2. CURREN : 1.0 AMPERE MAXIMUM PER CONTACT AT 30° C T-RISE.
- 2.3. TEMPERATURE : -55°C TO +85°C.

3.0. ELECTRICAL SPECIFICATION :

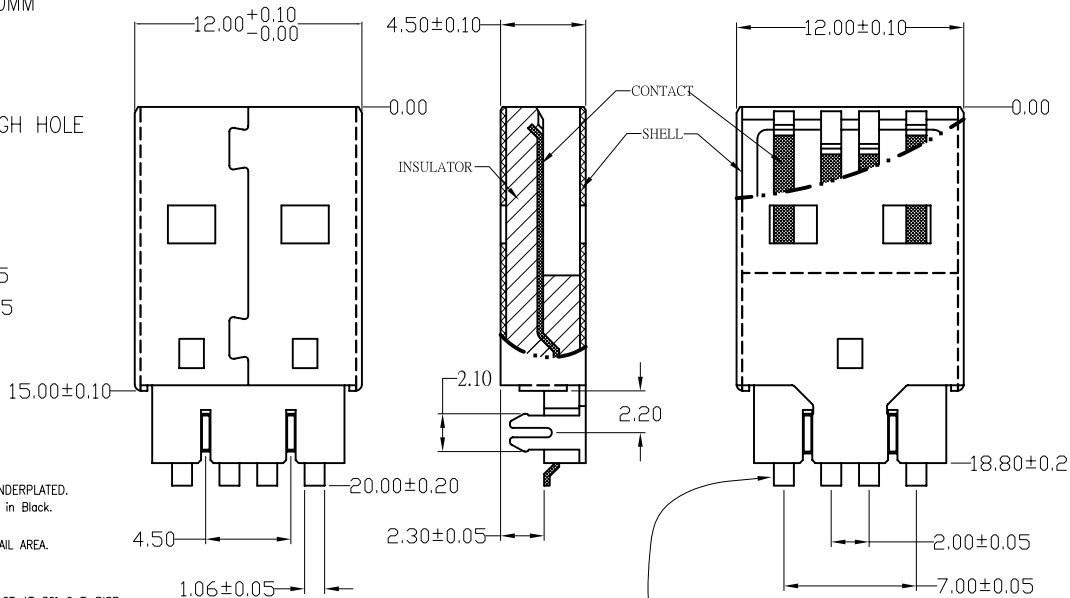
- 3.1. CONTACT RESISTANCE : 30 MILLIOHMS MAXIMUM INITIAL.
- 3.2. INSULATION RESISTANCE : 1,000 MEGOHMS MINIMUM.
- 3.3. DIELECTRIC WITHSTANDING VOLTAGE : 750 VAC AT SEE LEVER.

PACKING : A / TUBE

- 4.1. ONE TUBE CONTAINS 25Pcs CONNECTORS (L=325 M/M) AND
40 TUBES PACKED IN A WATERRESISTANT BAG .
 - 4.2. ONE CARTON CONTAINS 5000 Pcs CONNECTORS , G.W 14.5Kg 1.0 cubt
- PACKING : B / REEL
- 4.3. 1 REEL (OD=13") CONTAINS 800Pcs CONNECTORS
(REEL OD=13" . WIDTH=32.00m/m. PICH=16.00m/m).
 - 4.4. 1 CARTON CONTAINS 4800 Pcs CONNECTORS . G.W 14 Kg 1.5 cubt

5.0. PART NO : YUSVG30611

1=3u" GOLD PLATED OVER Ni UNDERPLATED
L PLATING : 3=30u" GOLD PLATED OVER Ni UNDERPLATED



Contact Insertmolding In Insulators

Remove burrs, Break sharp edges 0.4

R: max.

Stamp part no. in area indicated by "x"

Unless otherwise specified

Angle: ±1°

XX.X =±0.20 .X" =±

XX.XX =±0.10 .XX" =±

XX.XXX =±0.05 .XXX" =±

01	設計發行	CHEN 05/05/2004	料號	YUSVG3061X
	TITLE	USB-SMT Plug		
SHEET 1/1	App.	Date	Chk.	Date
SCALE 1:1	CHEN 06/05/2004	CHEN 05/07/2004	CHEN 05/03/2004	

1 譽盛精密工業股份有限公司